

Product Summary

V _{SB} Min	I _{PP} Max	C _T Typ
2.8V	5A	11pF

Description

Designed to replace multilayer varistors (MLVs) in portable applications where low operating voltage is vital, DIODES™ D3V3L1B2WS offers superior electrical characteristics such as lower clamping voltage and no device degradation when compared to MLVs. D3V3L1B2WS is designed to protect sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD), lightning, electrical fast transients (EFT), and cable discharge events (CDE).

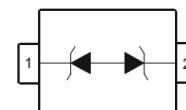
Applications

- Cellular handsets & accessories
- Notebooks & handhelds
- Portable instrumentation
- Digital cameras
- Peripherals
- MP3 players

SOD323



Top View



Device Schematic

Mechanical Data

- Package: SOD323
- Package Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish Annealed over Alloy 42 Leadframe (Lead-Free Plating). Solderable per MIL-STD-202, Method 208 e3
- Weight: 0.004 grams (Approximate)

Ordering Information (Note 4)

Part Number	Package	Marking	Reel Size (inches)	Tape Width (mm)	Packing	
					Qty.	Carrier
D3V3L1B2WS-7	SOD323	V / Λ	7	8	3,000	Tape & Reel

Notes:

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information



V / Λ = Product Type Marking Code

Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	Conditions
Peak Pulse Power Dissipation	P_{PP}	90	W	8/20 μs , per Figure 3
Peak Pulse Current	I_{PP}	5	A	8/20 μs , per Figure 3
ESD Protection – Contact Discharge	$V_{ESD_Contact}$	± 26	kV	Standard IEC 61000-4-2
ESD Protection – Air Discharge	V_{ESD_Air}	± 26	kV	Standard IEC 61000-4-2

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Package Power Dissipation (Note 5)	P_D	250	mW
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	500	°C/W
Operating Temperature Range	T_J	-55 to +125	°C
Storage Temperature Range	T_{STG}	-55 to +150	°C
Soldering Temperature, $t_{max} = 10s$	T_L	+260	°C

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Conditions
Reverse Working Voltage	V_{RWM}	—	—	3.3	V	—
Reverse Current (Note 5)	I_R	—	0.05	0.5	μA	$V_R = V_{RWM} = 3.3\text{V}$
Punch Through Voltage	V_{PT}	3.5	—	—	V	$I_R = 2\mu\text{A}$
Snap-Back Voltage	V_{SB}	2.8	—	—		$I_R = 50\text{mA}$
Reverse Clamping Voltage	V_{CL}	—	6.0	8.0	V	$I_{PP} = 1\text{A}, t_p = 8/20\mu\text{s}$
		—	8.5	18		$I_{PP} = 5\text{A}, t_p = 8/20\mu\text{s}$
Capacitance	C_T	—	11	15	pF	$V_R = 0\text{V}, f = 1\text{MHz}$

Note: 5. Device mounted on FR-4 PCB pad layout (2oz copper) as shown in Diodes Incorporated's package outline PDFs, which can be found on our website at <http://www.diodes.com/package-outlines.html>.

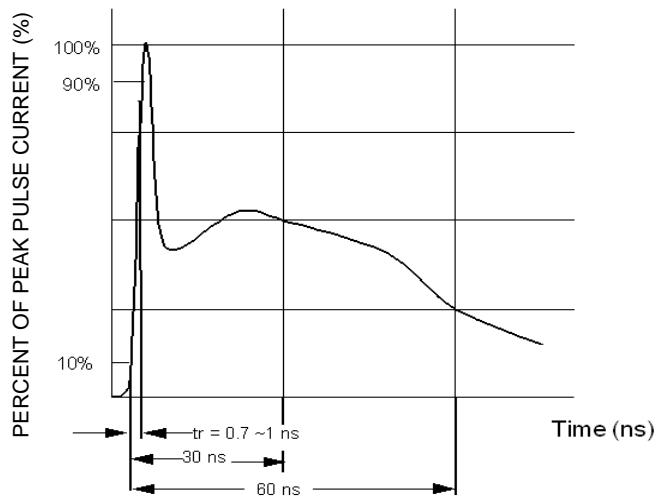


Figure 1. ESD Pulse Waveform According to IEC 61000-4-2

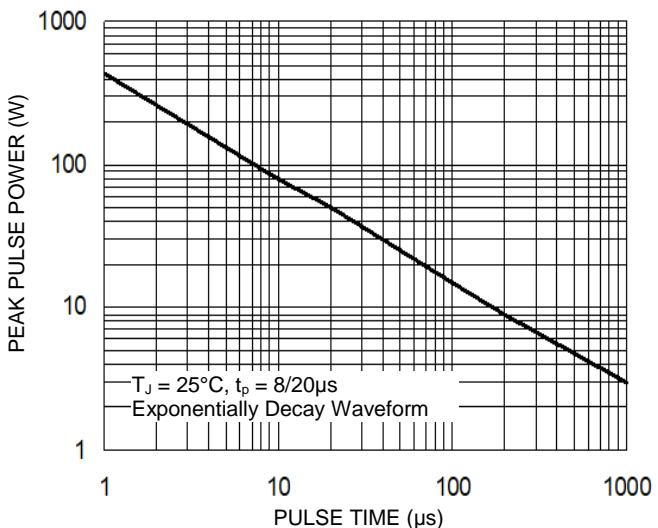


Figure 2. Power Dissipation vs. Pulse Time

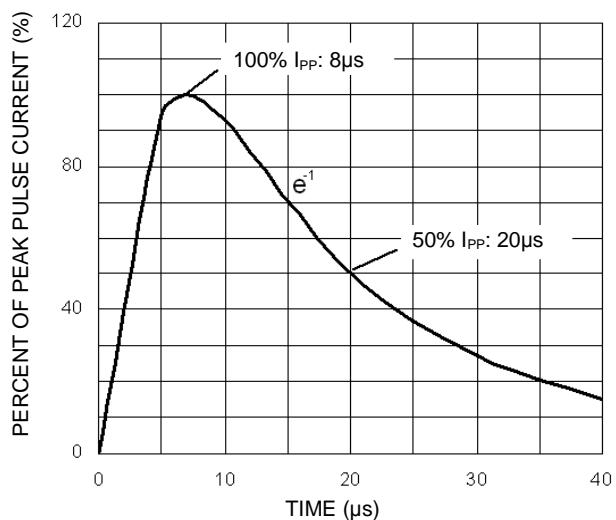


Figure 3. Typical 8 x 20μs Pulse Waveform

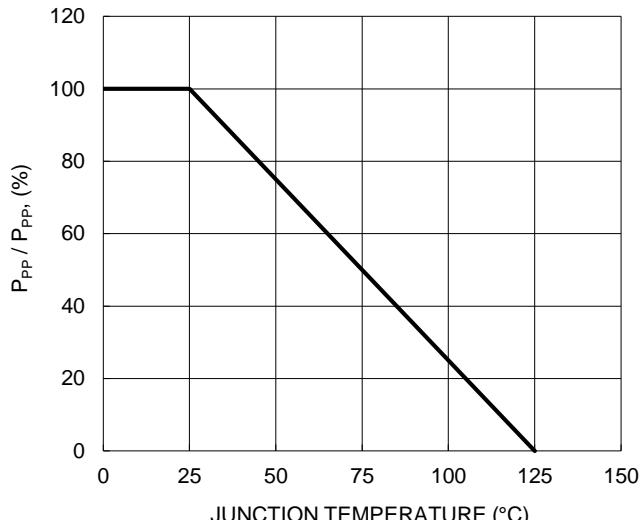


Figure 4. Peak Pulse Power vs. T_J

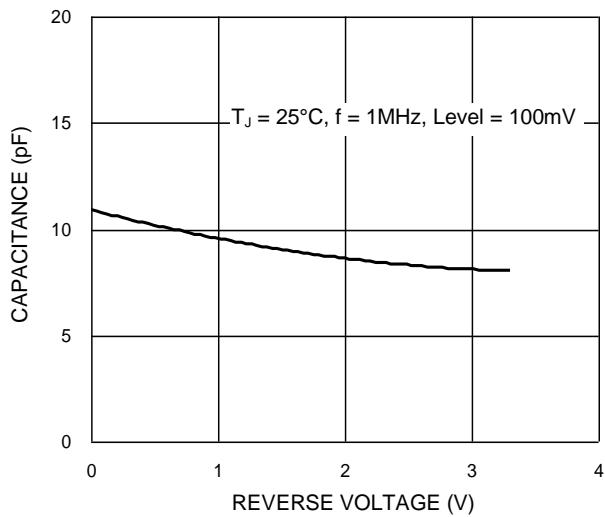


Figure 5. Typical Junction Capacitance

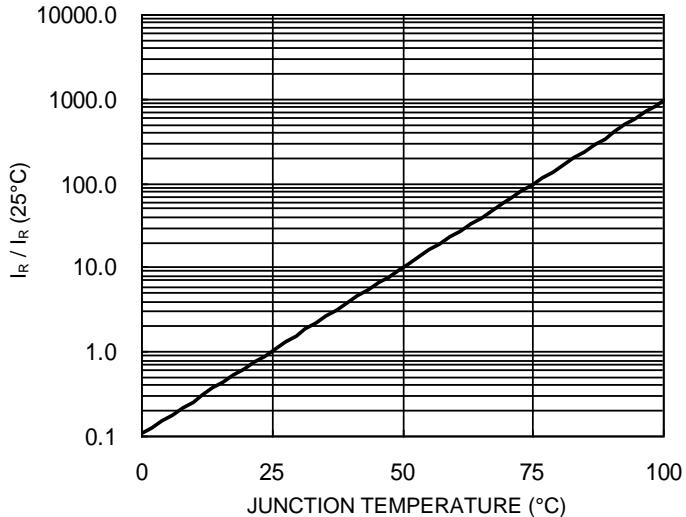
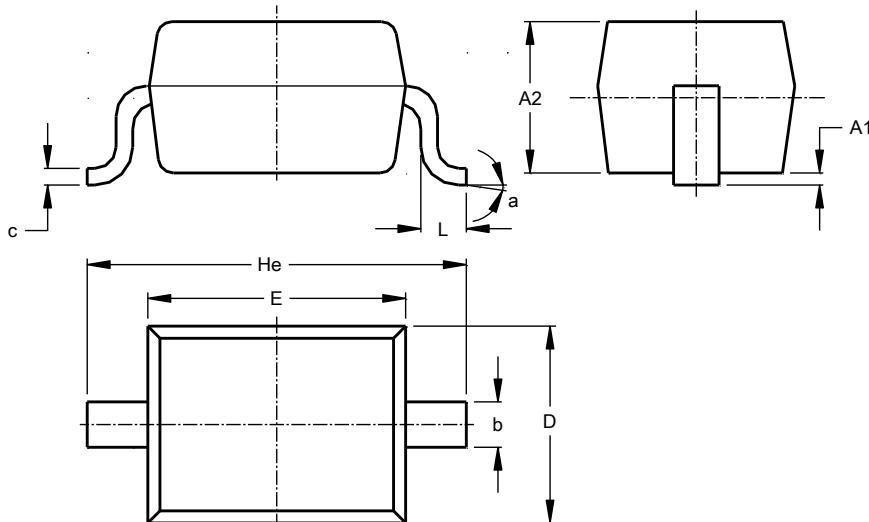


Figure 6. Reverse Leakage Current vs. T_J

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOD323



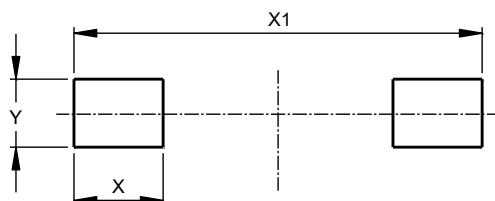
SOD323			
Dim	Min	Max	Typ
A1	--	0.10	0.05
A2	1.00	1.10	1.05
b	0.25	0.35	0.30
c	0.10	0.15	0.11
D	1.20	1.40	1.30
E	1.60	1.80	1.70
He	2.30	2.70	2.50
L	0.20	0.40	0.30
a	0°	8°	--

All Dimensions in mm

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOD323



Dimensions	Value (in mm)
X	0.590
X1	2.700
Y	0.450

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